Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: DQA 010 MSOP 3x3x1.0mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Commediation Device Typ	J. J., ("Contained In"	% Total							
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	11.67	(mg) Total	Mold Compound	% ot Total Weight	47.62
Silica, vitreous	60676-86-0	Mold Compound	40.477	9.917	404,770		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	2.917	0.715	29,167		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	2.917	0.715	29,167		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.167	0.286	11,667		Epoxy, Cresol Novolac		2.45	
Carbon Black	1333-86-4	Mold Compound	0.143	0.035	1,429		Carbon Black	1333-86-4	0.30	
Copper(Cu)	7440-50-8	Lead Frame	39.336	9.637	393,362			Total	100.00	
Nickel (Ni)	7440-02-0	Lead Frame	1.227	0.301	12,267	10.02	(mg) Total	Lead Frame	% of Total Weight	40.89
Silicon (Si)	7440-21-3	Lead Frame	0.266	0.065	2,658		Copper(Cu)	7440-50-8	96.20	
Magnesium (Mg)	7439-95-4	Lead Frame	0.061	0.015	613		Nickel (Ni)	7440-02-0	3.00	
Silver (Ag) Proprietary Resin	7440-22-4 Trade Secret	Die Attach Die Attach	1.366 0.322	0.335 0.079	13,659 3,219		Silicon (Si) Magnesium (Mg)	7440-21-3 7439-95-4	0.65 0.15	
			0.322		522		wagnesium (wg)		100.00	
Proprietary Curing agent & Hardener Silicon	Trade Secret 7440-21-3	Die Attach Chip (Die)	6.570	0.013 1.610	65,700	0.43	() T - (-1	Total		474
		- 1 (-)	0.640		6.400	0.43	(mg) Total	Die Attach	% of Total Weight	1.74
Gold Nickel	7440-57-5 7440-02-0	Wire Bond Plating on external leads (pins)	2.286	0.157 0.560	22.860		Silver (Ag) Proprietary Resin	7440-22-4 Trade Secret	78.50 18.50	
		Plating on external leads (pins)	0.127	0.031	1,270	Dee	prietary Curing agent & Han		3.00	
	7440 05 2					PIO			3.00	
Palladium	7440-05-3			0.024	1 270				400.00	
	7440-05-3 7440-57-5	Plating on external leads (pins)	0.127	0.031	1,270	4.04	4	Total	100.00	0.57
Palladium Gold semiconductor device and its homogenous 863/EU (31 March 2015) and 2002/53/EC (Er	7440-57-5 0.0245 materials comply witd-of-Life Vehicles (E	Plating on external leads (pins) TOTALS g Total Mass th EU Directives: 2002/95/EC (27 January 2003) LV) without exemption (zero)	0.127 : 100.000 & Directive 201	24.500 1/65/EU (08 Ju	1,000,000	1.61	Total (mg) Doped Silicon	Total Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	6.57
Palladium Gold Semiconductor device and its homogenous 863/EU (31 March 2015) and 2002/53/EC (Er bliance with the above EU Directives has been	7440-57-5 0.0245 materials comply with the description of the complete of th	Plating on external leads (pins) TOTALS g Total Mass h EU Directives: 2002/95/EC (27 January 2003) LV) without exemption (zero) al design controls, supplier declarations, and /o	0.127 i: 100.000 & Directive 201 or analytical test of	24.500 1/65/EU (08 Ju data.	1,000,000 ine 2011) and	1.61 0.16	Total (mg)	Total Chip (Die) 7440-21-3	% of Total Weight 100.00	6.57 0.64
Palladium Gold semiconductor device and its homogenous 863/EU (31 March 2015) and 2002/53/EC (Er bliance with the above EU Directives has beenemical substance is absent from the list ab chip Technology Incorporated's knowledge	7440-57-5 0.0245 materials comply with dof-Life Vehicles (Early verified via internative, the chemical surand belief as of the	Plating on external leads (pins) TOTALS g Total Mass th EU Directives: 2002/95/EC (27 January 2003) LV) without exemption (zero)	0.127 c: 100.000 & Directive 201 or analytical test of semiconductor of the control to the cont	24.500 1/65/EU (08 Ju data. device and, to t tt the unavoidal	1,000,000 ine 2011) and the best of	-	Total (mg) Doped Silicon	Total Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	
Palladium Gold semiconductor device and its homogenous 863/EU (31 March 2015) and 2002/53/EC (Er bliance with the above EU Directives has been the memical substance is absent from the list ab chip Technology Incorporated's knowledge entration of the chemical substance, if any,	0.0245 0.0245 materials comply will d-of-Life Vehicles (E in verified via interna- ove, the chemical su and belief as of the s not below the thre UL94 V0 flammabilit	Plating on external leads (pins) TOTALS g Total Mass h EU Directives: 2002/95/EC (27 January 2003) LV) without exemption (zero) al design controls, supplier declarations, and /c ibstance is NOT an intentional ingredient in the date of this document, there is no credible reas shold of regulatory concern for any regulatory y standard for plastics. You can access the UL	0.127 c: 100.000 & Directive 201 or analytical test of semiconductor of the control of the cont	24.500 1/65/EU (08 Ju data. device and, to t tt the unavoidal ide.	1,000,000 ine 2011) and the best of ble impurity	-	Total (mg) Doped Silicon (mg) Total	Total Chip (Die) 7440-21-3 Total Wire Bond	% of Total Weight 100.00 100.00 % of Total Weight	
Palladium Gold semiconductor device and its homogenous 863/EU (31 March 2015) and 2002/53/EC (Er bliance with the above EU Directives has been emical substance is absent from the list ab- chip Technology Incorporated's knowledge entration of the chemical substance, if any, ng compounds used by Microchip meet the tat http://ul.com/global/eng/pages/offerings- protective "tubes" in which the specific proce outer box and certain "reels" may be mad	0.0245 naterials comply wild-of-Life Vehicles (Ein verified via internative, the chemical suand belief as of the snot below the thre UL94 V0 flammabilit findustries/chemical uct is shipped are me from PVC plastic.	Plating on external leads (pins) TOTALS g Total Mass the U Directives: 2002/95/EC (27 January 2003) LV) without exemption (zero) al design controls, supplier declarations, and /o abstance is NOT an intentional ingredient in the date of this document, there is no credible reas shold of regulatory concern for any regulatory y standard for plastics. You can access the UL s/plastics/ adde from polyvinyl chloride (PVC) plastic. "Wir	0.127 c 100.000 & Directive 201 or analytical test of semiconductor of semiconductor of semiconductor of the semi	24.500 1/65/EU (08 Ju data. device and, to t tt the unavoidal ide. atabases to oblused to hold the	1,000,000 the 2011) and the best of ble impurity tain a test	-	Total (mg) Doped Silicon (mg) Total	Total Chip (Die) 7440-21-3 Total Wire Bond 7440-57-5	% of Total Weight 100.00 100.00 % of Total Weight 100.00	
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